Silicom

Connectivity Solutions

uCPE Medium

Intel® Xeon™ D-1500 and Broadcom® Hurricane3 based uCPE

Product Description

Silicom's uCPE based on the Intel® Xeon™ D-1500 and Broadcom® Hurricane3 product line is a highly flexible network edge device that brings the agility of modular LAN, WAN, management, and compute to cost-sensitive applications in SD-WAN, CPE, Security, Small Cell, MEC, vRAN, Cell Site, Cloud Edge, Aggregation Router and IoT.



With a new type of modularity x86 and networking switch engine designed specifically for networking application. Silicom uCPE is the ideal platform upon which to deploy next-generation edge applications.

Technical Specifications

General Technical Specifications			
CPU	Intel® Xeon™ D-1541 8Cores, 16 threads Base Freq. 2.1GHz, 14MB Cache, TDP 45W		
	Platform will also support Xeon-D NS SKU's		
BIOS	UEFI BIOS		
BIOS Flash	SPI		
Switch Chips set:	Broadcom® Hurricane2 BCM56160		
Copper PHY:	Embedded CuGPHY, BCM56160		
MGMT PHY:	Broadcom® B50210S		
Memory:	32GB DDR4 with ECC, 2x channels DDR4 DIMMs, 2 x 16GByte SODIMM		
Storage:	500GB /SSD, M2, SATA		
Internal Switch:	2x 10GE-KR		
	Additional 2x10GE-KR with Xeon-D NS SKU's		
External Switch Ports:	10x 1GbE RJ45		
	4x SFP+		

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	4 of 1GbE supports POE+*		
	*Total Power POE+ power limit is 65W		
	Dynamic power load based on actual power consumption		
	1GbE RJ45 on Management Card, Shared with BMC.		
Host Mgmt:	1GbE Between BMC and Switch		
USB 3.0:	2xFront, 2x Internal Vertical		
Serial Console:	RJ45 connector using RS232 signaling		
	M.2 Key-B, support 3042 Card. Externally accessible SIM card supported.		
LTE:	Mini PCIe supporting USB2.0/3.0 and externally accessible SIM card.		
WiFi:	Not supported		
M.2 Expansion	M.2 Key B with support up to 30x110mm. Currently used for M.2 Storage		
	Will Rey D with support up to sox Fromm. Our only used for Will blorage		
BMC:	μBMC		
Dino.	μοινο		
	TPM 2.0 – Compute		
TPM:			
	TPM2.0 – Module		
	90-264VAC input,		
Power:	12VDC, 125W		
	54VDC, 65W		
	Dying Gasp supported on BMC		
LED's:	Management card support three tri-color configurable LED's (red, green, blue)		
Other Hardware:	Configurable Recessed button (Recommend for Factory reset)		
	Configurable Large button (Recommend for power)		
Form Factor:	1U rackmount Form Factor EIA 19"		
	$(WxDxH) = 430 \times 411 \times 44mm$		
Expansion / Voice Module	PCIe x16: Support for either Voice module or 2/ M4 module. Support for Voice module is		
	connected directly to the CPU board.		
	In order to support M4 module, needs to install mid plan expansion kit. Mid plan kit is not part		
	of BOM		
Weight:	5.46kg (192.6oz)		
	Maximum: 90-130Vac 50-60Hz 4.6A / 200-240Vac 50-60Hz 2.4A		
Power Consumption:	Typical: 90-130Vac 50-60Hz 2.2A / 200-240Vac 50-60Hz 1.1A		
	The total power consumption of the card depends on user application		
Cooling	EANS Number of Eans TRD Design supports 5 EAN front to back sittlew		
Cooling:	FANs, Number of Fans TBD, Design supports 5 FAN, front-to-back airflow		

Sensors/Monitors:	Thermal protection Critical Error Detection Voltage monitors Current protection	
Operating Temperature:	0°C – 40°C (32°F – 104°F)	
Storage:	-40°C–65°C (-40°F–149°F)	
Regulation:	CE, FCC Class A, ROHS requirements.	
MTBF*:	57156 hours * According to Telcordia SR-332 Issue 4. Environmental condition – GB (Ground, Fixed, and Controlled). Ambient temperature 40°C	

Order Information

P/N	Description	Notes
80500-0180-G20	vECPE, 1U,19",D1541(8C),DDR4/32GB/ECC,2xPS	Top level – Shippable kit, including packaging, GA candidate